

L Number	Hits	Search Text	DB	Time stamp
1	1349	heat adj sink with coolant	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/15 09:17
2	169	(heat adj sink) with coolant and (integrated adj circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/15 10:41
4	95	substrate with coolant and (integrated adj circuit) and solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/15 10:42
3	279	substrate with coolant and (integrated adj circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/15 11:39